

SOT-23 Plastic-Encapsulate MOSFETS

LJ2294B

N-Channel Enhancement Mode Power MOSFET

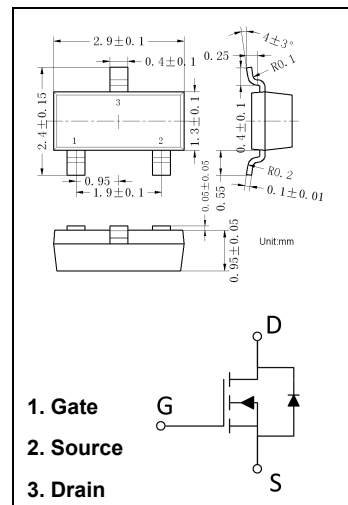
Features

- $V_{DS} = 110V$, $I_D = 3A$
- $R_{DS(ON)} < 240m\Omega$ @ $V_{GS} = 10V$ (Typ:210m Ω)
- High density cell design for ultra low R_{dson}
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

Marking: In8



Maximum Ratings ($T_a=25^\circ C$ unless otherwise specified)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source voltage	110	V
V_{GS}	Gate-Source voltage	± 20	
I_D	Drain Current-Continuous	3	A
I_{DM}	Pulsed Drain Current ¹⁾	10	
P_D	Power Dissipation ²⁾	1.25	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ C$

Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Maximum Junction-to-Ambient ²⁾	100	$^\circ C/W$

Electrical Characteristics (T_J=25°C unless otherwise specified)

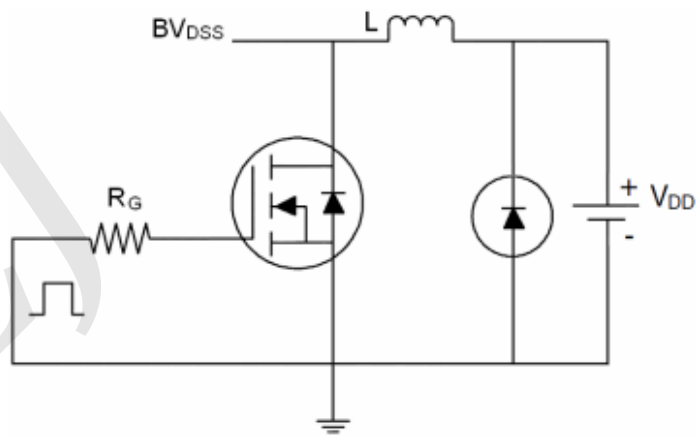
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	110	115		V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 110V, V _{GS} = 0V			1	μA
I _{GSS}	Gate-body Leakage current	V _{DS} = 0V, V _{GS} = ±20V			±100	nA
V _{GS(th)}	Gate-Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1.2	1.8	2.5	V
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} = 10V, I _D = 1A		210	260	mΩ
g _{fs}	Forward Trans conductance	V _{DS} = 5V, I _D = 1A	1			S
Dynamic ⁴⁾						
C _{iss}	Input Capacitance	V _{GS} = 0V V _{DS} = 50V f = 1.0MHz		190		pF
C _{oss}	Output Capacitance			22		
C _{rss}	Reverse Transfer Capacitance			13		
Switching ⁴⁾						
Q _g	Total Gate Charge	V _{GS} = 10V, I _D = 1.3A, V _{DS} = 50V		5.2		nC
Q _{gs}	Gate-Source Charge			0.75		
Q _{gd}	Gate-Drain Charge			1.4		
t _{d(on)}	Turn-On Delay Time	V _{DD} = 50V, I _D = 1.3A, R _L = 39Ω V _{GS} = 10V, R _G = 1Ω		6		ns
t _r	Rise Time			10		
t _{d(off)}	Turn-Off Delay Time			10		
t _f	Fall Time			6		
Drain-Source Diode Characteristics						
V _{SD}	Diode Forward Voltage ³⁾	I _S = 1A, V _{GS} = 0V			1.2	V
I _S	Maximum Body-Diode Continuous Current ²⁾				2	A

Notes

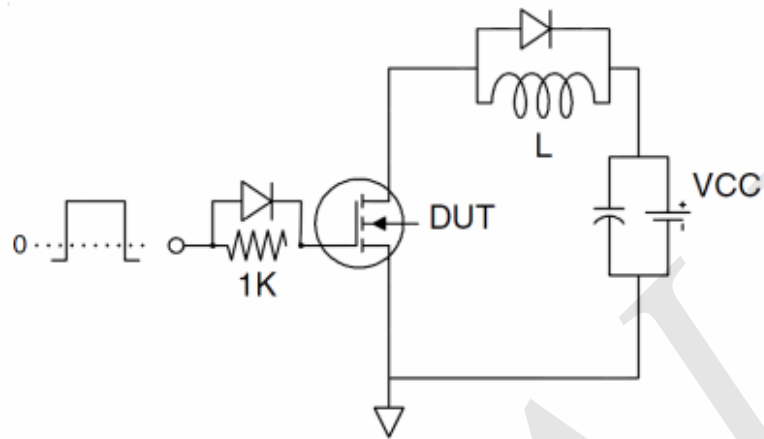
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

Test Circuit

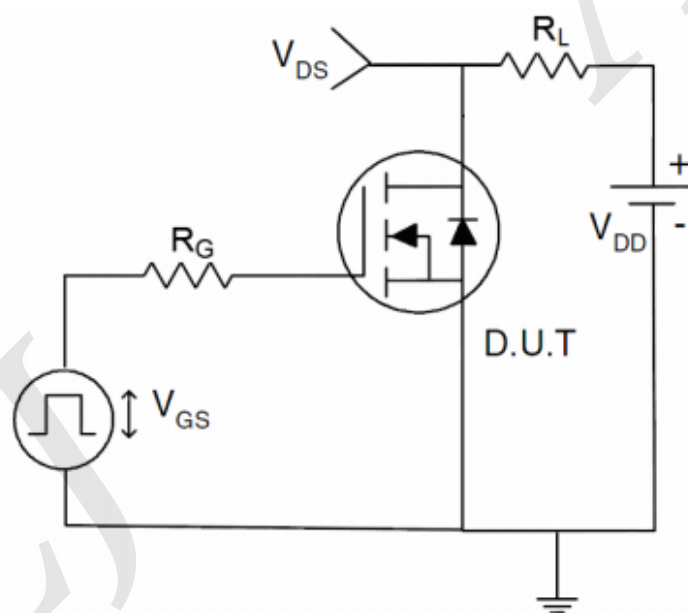
1) E_{AS} test circuit



2) Gate charge test circuit



3) Switch Time Test Circuit



Typical Characteristics and Thermal Characteristics (Curves)

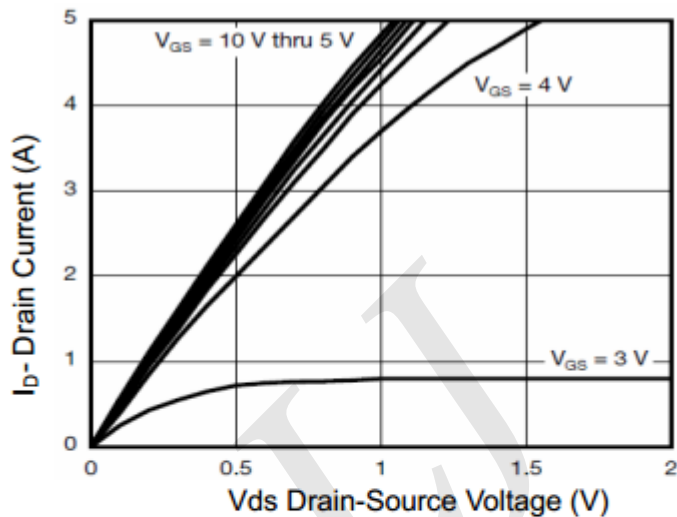


Figure 1 Output Characteristics

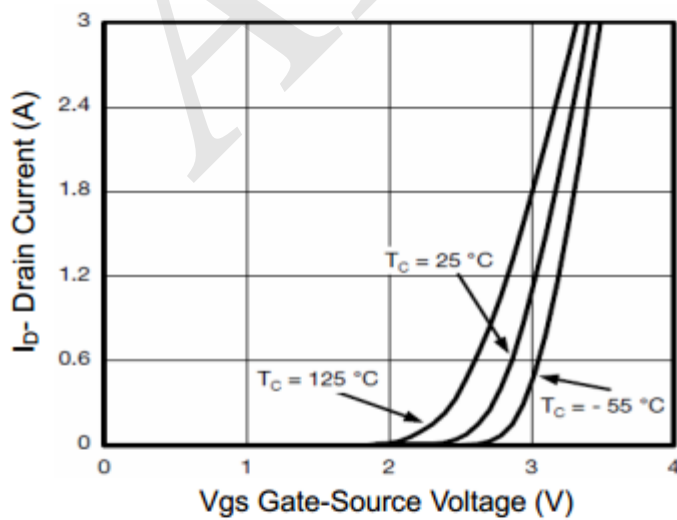


Figure 2 Transfer Characteristics

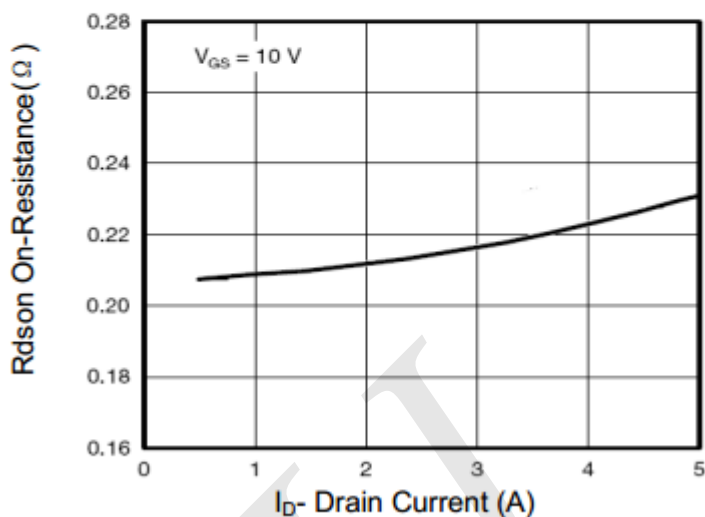


Figure 3 $R_{DS(on)}$ - Drain Current

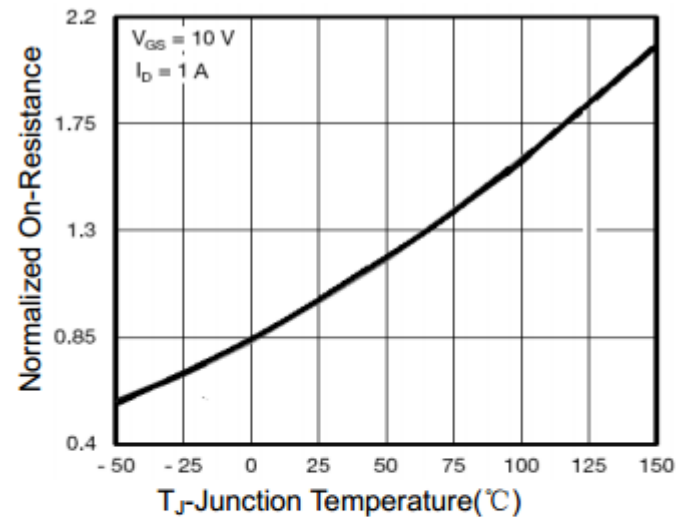


Figure 4 $R_{DS(on)}$ -Junction Temperature

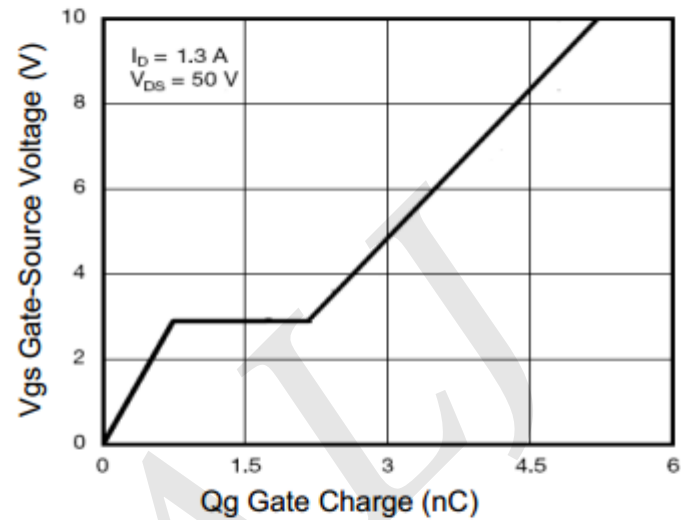


Figure 5 Gate Charge

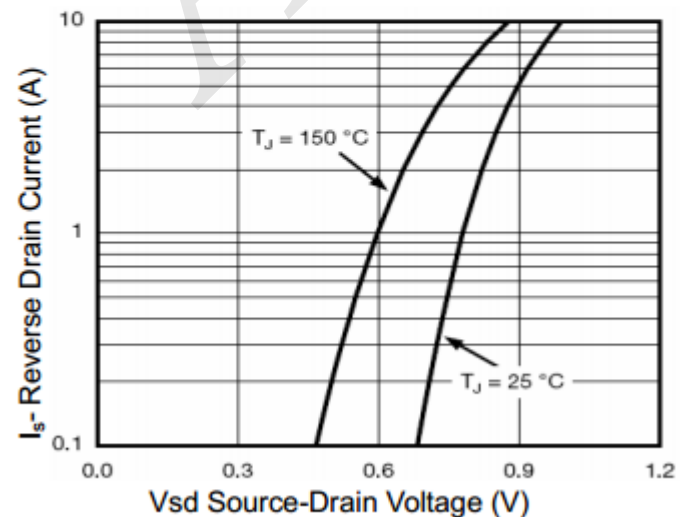


Figure 6 Source- Drain Diode Forward

Typical Characteristics and Thermal Characteristics (Curves) (Cont.)

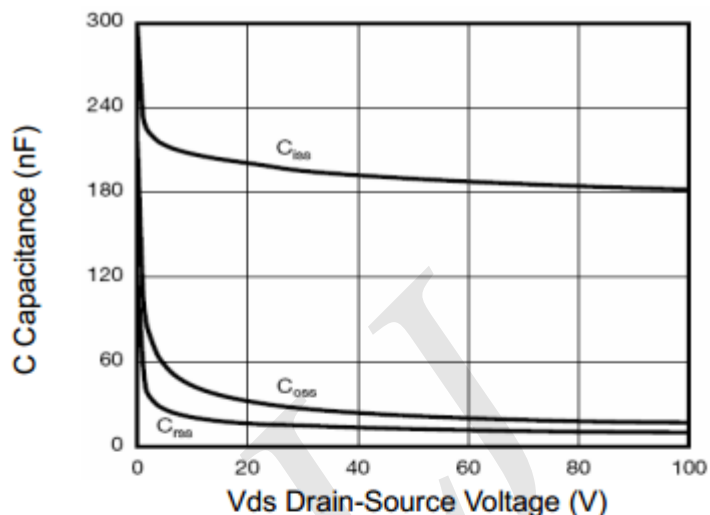


Figure 7 Capacitance vs Vds

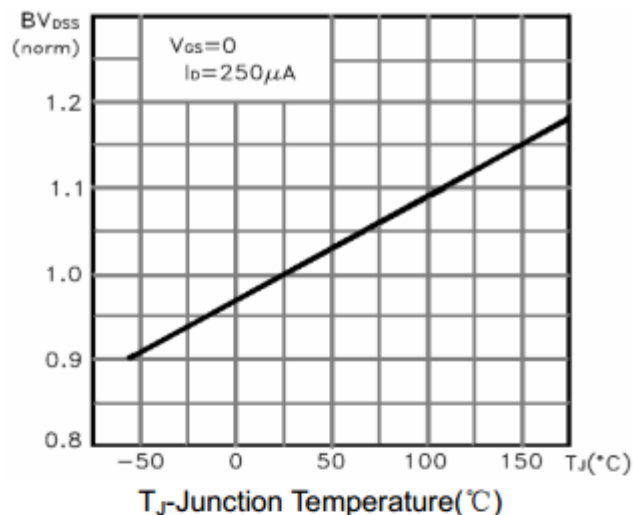


Figure 9 BV_{DSS} vs Junction Temperature

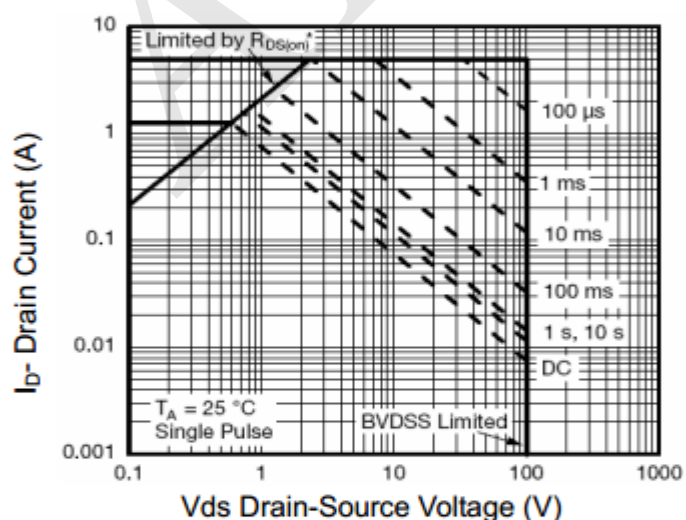


Figure 8 Safe Operation Area

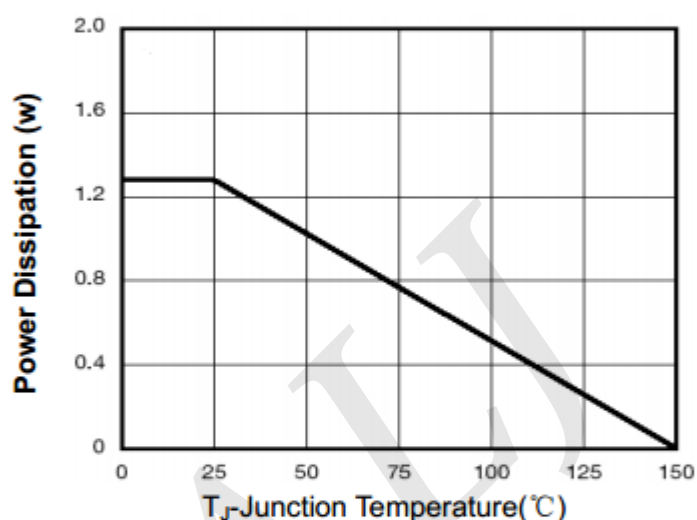


Figure 10 Power De-rating

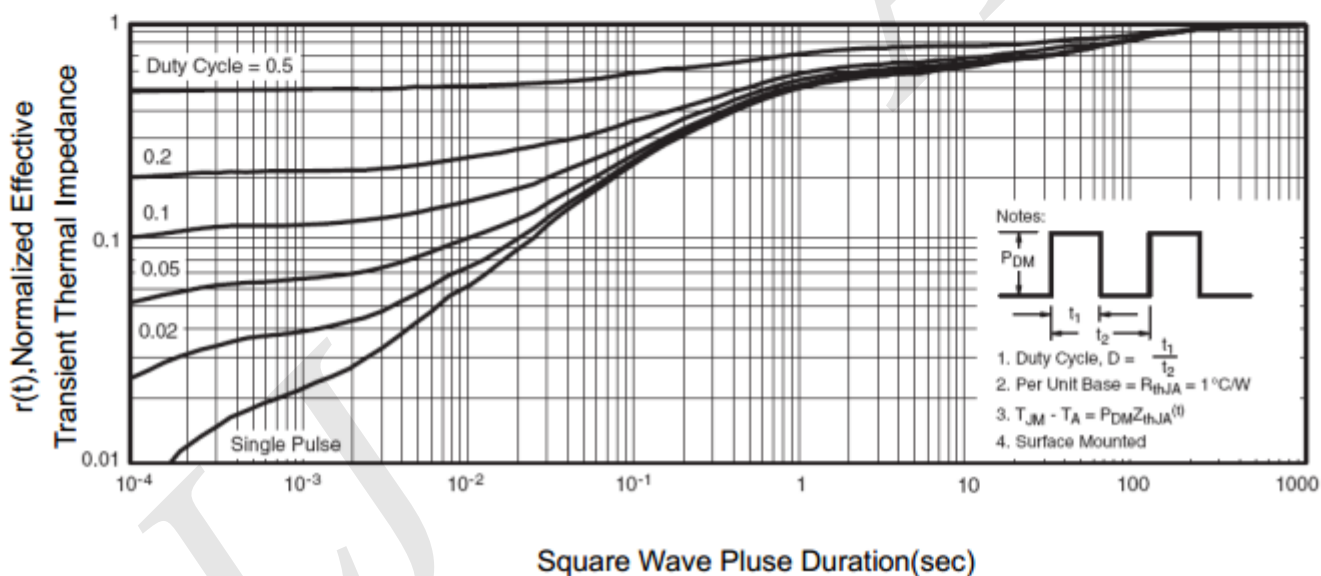


Figure 11 Normalized Maximum Transient Thermal Impedance